

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	266	(206/711).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/09/27 11:41
L2	307	(206/710).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/09/27 11:41
L3	123	1 not "23"	US-PGPUB; USPAT	OR	ON	2006/09/27 11:41
L4	307	2	US-PGPUB; USPAT	OR	ON	2006/09/27 11:41
L5	207	1 not 2	US-PGPUB; USPAT	OR	ON	2006/09/27 13:40
L6	295	cassette.clm. and (substrate wafer workpiece semiconductor). clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 PREVENT\$4 FILL\$4). CLM. AND (PRESSURE VACUUM)	US-PGPUB; USPAT	OR	ON	2006/09/27 13:51
L7	3101	(cassette HOLDER CONTAINER SMIF POD FOUP).clm. and (substrate wafer workpiece semiconductor).clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 PREVENT\$4 FILL\$4).CLM. AND (PRESSURE VACUUM)	US-PGPUB; USPAT	OR	ON	2006/09/27 13:51
L8	2068	(cassette HOLDER CONTAINER SMIF POD FOUP) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 PREVENT\$4 FILL\$4) AND (PRESSURE VACUUM)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:50
L9	2070	(cassette HOLDER CONTAINER SMIF POD FOUP) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 PREVENT\$4 FILL\$4 PROHIBIT\$4) AND (PRESSURE VACUUM)	EPO; JPO; DERWENT	OR	ON	2006/09/27 15:11
L10	1179	(cassette HOLDER CONTAINER SMIF POD FOUP) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (PRESSURE VACUUM)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:50
L11	230	cassette.clm. and (substrate wafer workpiece semiconductor). clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4).CLM. AND (PRESSURE VACUUM)	US-PGPUB; USPAT	OR	ON	2006/09/27 13:53
L12	36	cassette.clm. and (substrate wafer workpiece semiconductor). clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4).CLM. AND (screw\$4 fasten\$4 bolt\$4).clm.	US-PGPUB; USPAT	OR	ON	2006/09/27 13:53
L13	220	cassette.clm. and (substrate wafer workpiece semiconductor). clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4).CLM. AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4).clm.	US-PGPUB; USPAT	OR	ON	2006/09/27 13:53
L14	2478	(cassette HOLDER CONTAINER SMIF POD FOUP).clm. and (substrate wafer workpiece semiconductor).clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4).CLM. AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4).clm.	US-PGPUB; USPAT	OR	ON	2006/09/27 14:16

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L15	2256	(cassette HOLDER CONTAINER SMIF POD FOUP) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:55
L16	1038	(cassette HOLDER CONTAINER SMIF POD FOUP) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4) and (corner edge side wall side\$1wall)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:56
L17	438	(cassette HOLDER CONTAINER SMIF POD FOUP carrier) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4) and (corner edge side wall side\$1wall) and (load\$3 transfer\$4 transport carry\$4)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:57
L18	95	(cassette HOLDER CONTAINER SMIF POD FOUP carrier) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4) and (corner edge side wall side\$1wall) and (load\$3 transfer\$4 transport carry\$4) and (vacuum pressure)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:57
L19	106	(cassette HOLDER CONTAINER SMIF POD FOUP carrier) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4) and (corner edge side wall side\$1wall) and (load\$3 transfer\$4 transport carry\$4) and (vacuum pressure evacuat\$4 exhaust\$4)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:57
L20	106	(cassette HOLDER CONTAINER SMIF POD FOUP carrier) and (substrate wafer workpiece semiconductor) and (hole opening through\$1hole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4) AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4) and (corner edge side wall side\$1wall) and (load\$3 transfer\$4 transport carry\$4) and (vacuum pressure evacuat\$4 exhaust\$4)	EPO; JPO; DERWENT	OR	ON	2006/09/27 13:58
L21	264	(cassette HOLDER CONTAINER SMIF POD FOUP).clm. and (substrate wafer workpiece semiconductor).clm. and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT).CLM. and (cover\$4 obstruct\$4 block\$4 CLOG\$4 FILL\$4).CLM. AND (screw\$4 fasten\$4 bolt\$4 fix\$4 attach\$4 connect\$4).clm. and (vacuum pressure evacuat\$4 exhaust\$4).clm. and (corner edge side wall side\$1wall).clm. and (load\$3 transfer\$4 transport carry\$4).clm.	US-PGPUB; USPAT	OR	ON	2006/09/27 14:39
L22	1	("5198243").PN.	US-PGPUB; USPAT	OR	OFF	2006/09/27 14:47
L23	19	156/345.51.ccls. and (cassette carrier).clm.	US-PGPUB; USPAT	OR	ON	2006/09/27 14:49
L24	82	156/345.31.ccls. and (cassette carrier).clm.	US-PGPUB; USPAT	OR	ON	2006/09/27 14:59
L25	100	414/331.01	US-PGPUB; USPAT	OR	ON	2006/09/27 15:02
L26	248	"414"/\$.ccls. and cassette.ti.	US-PGPUB; USPAT	OR	ON	2006/09/27 15:02

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L27	105	414/217.1.ccls. and (cassette HOLDER CONTAINER SMIF POD FOUP) and (substrate wafer workpiece semiconductor) and (hole opening throughhole aperture orifice outlet inlet port vent gap crevice crack chink SLOT SLIT) and (cover\$4 obstruct\$4 block\$4 CLOG\$4 PREVENT\$4 FILL\$4 PROHIBIT\$4) AND (PRESSURE VACUUM)	US-PGPUB; USPAT	OR	ON	2006/09/27 15:12
S7	66	(cassette pod "foup" "smif") same (hole with (cover\$3 obstruct\$4))	US-PGPUB; USPAT	OR	ON	2006/01/05 18:35
S8	935	(cassette pod "foup" "smif") same (hole with (cover\$3 obstruct\$4))	US-PGPUB; USPAT	OR	ON	2006/01/05 17:56
S9	131	(cassette pod "foup" "smif") same (hole with (cover\$3 obstruct\$4) same (arm robot hand))	US-PGPUB; USPAT	OR	ON	2006/01/05 17:57
S10	131	(cassette pod "foup" "smif") same (hole with (cover\$3 obstruct\$4)) same (arm robot hand)	US-PGPUB; USPAT	OR	ON	2006/01/05 17:57
S11	68	((cassette pod "foup" "smif") with hole with (cover\$3 obstruct\$4)) same (arm robot hand)	US-PGPUB; USPAT	OR	ON	2006/01/05 17:58
S12	10	((cassette pod "foup" "smif") with hole with (cover\$3 obstruct\$4)) same (arm robot hand) same (wafer substrate semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:01
S13	4	((cassette pod "foup" "smif") with hole with (block\$4)) same (arm robot hand) same (wafer substrate semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:01
S14	6	((cassette pod "foup" "smif") with hole with (block\$4)) same (wafer substrate semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:01
S15	2	(cassette pod "foup" "smif") with hole with (block\$3 cover\$3 obstruct\$4) with (substrate wafer semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:03
S16	3	(cassette pod "foup" "smif") with hole with (block\$3 cover\$3 obstruct\$4) with (substrate wafer semiconductor workpiece)	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:05
S17	11	(cassette pod "foup" "smif") same (hole opening orifice) same (block\$3 cover\$3 obstruct\$4) same (substrate wafer semiconductor workpiece) same (arm tool robot hand transfer\$4 transport\$4 convey\$4)	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:07
S18	105	(cassette pod "foup" "smif") same (hole opening orifice) same (block\$3 cover\$3 obstruct\$4) same (substrate wafer semiconductor workpiece) same (arm tool robot hand transfer\$4 transport\$4 convey\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:23
S19	330	((hole opening orifice) same (block\$3 cover\$3 obstruct\$4) same (arm tool robot hand transfer\$4 transport\$4 convey\$4)) and 414/935-941.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/09 14:52
S20	64	(cassette same (hole opening orifice) same (block\$3 cover\$3 obstruct\$4) same (arm tool robot hand transfer\$4 transport\$4 convey\$4)) and 414/935-941.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:24
S21	81	((cassette pod "foup") same (hole opening orifice) same (block\$3 cover\$3 obstruct\$4) same (arm tool robot hand transfer\$4 transport\$4 convey\$4)) and 414/935-941.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:25
S22	21	((cassette pod "foup") with (hole opening orifice) with (block\$3 cover\$3 obstruct\$4) with (arm tool robot hand transfer\$4 transport\$4 convey\$4)) and 414/935-941.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:28
S23	385	((cassette pod "foup") with (hole opening orifice) with (block\$3 cover\$3 obstruct\$4) with (arm tool robot hand transfer\$4 transport\$4 convey\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:28
S24	65	((cassette pod "foup") with (hole opening orifice) with (block\$3 cover\$3 obstruct\$4) with (arm tool robot hand transfer\$4 transport\$4 convey\$4) with (bottom lower))	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:29
S25	74	((cassette pod "foup") with (hole opening orifice) with (block\$3 cover\$3 obstruct\$4) with (arm tool robot hand transfer\$4 transport\$4 convey\$4) with (bottom lower base))	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:29

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S26	41	((cassette pod "foup") with (hole opening orifice) with (block\$3 cover\$3 obstruct\$4) with (arm tool robot hand transfer\$4 transport\$4 convey\$4) with (bottom lower base) with (side\$1wall wall side))	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:30
S27	1	jiang-i-tiang.in. peng-yu-ling.in. cheng-kuo-shun.in.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/05 18:31
S28	0	jiang-i-tiang.in. peng-yu-ling.in. cheng-kuo-shun.in.	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:32
S29	2833	au.as. optronics.as.	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:32
S30	4	S29 and (cassette pod "foup")	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:34
S31	4	S29 and (cassette pod "foup" "smif")	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:34
S32	437	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:36
S33	3273558	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side) iwith (bottom lower)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:37
S34	105	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side) with (bottom lower)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:37
S35	1	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side) with (bottom lower) with (block\$3 obstruct\$3 cover\$3) with (prohibit\$3 prevent\$3)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:38
S36	4	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side) with (block\$3 obstruct\$3 cover\$3) with (prohibit\$3 prevent\$3)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:39
S37	47	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side) with (block\$3 obstruct\$3 cover\$3)	US-PGPUB; USPAT	OR	ON	2006/01/05 18:42
S38	10	(casssette pod "foup" "smif") with (hole opening orifice) with (wall side\$1wall side) with (block\$3 obstruct\$3 cover\$3)	EPO; JPO; DERWENT	OR	ON	2006/01/05 18:42
S39	272	(206/710).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/09/27 11:40
S40	5	("4129211" "4668484" "5377476" "5713711" "5810537").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 14:12
S41	1	("6540467").URPN.	USPAT	OR	ON	2006/01/06 16:19
S42	480	((414/266) or (414/267) or (220/661)).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/01/06 16:19
S43	189963	((wall with side) (side\$1wall)) with (hole orifice cut\$1out opening)	US-PGPUB; USPAT	OR	ON	2006/01/06 16:23
S44	55	S42 and S43	US-PGPUB; USPAT	OR	ON	2006/01/06 16:21
S45	1	S42 and S43 and (substrate wafer semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/06 16:21
S46	30925	((wall with side) (side\$1wall)) with (hole orifice cut\$1out opening)) and (substrate wafer semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/06 16:23
S47	13	(((wall with side) (side\$1wall)) with (hole orifice cut\$1out opening) with (obstruct\$4 cover\$4 clos\$4 block\$4) with (prevent\$4 prohibit\$4) with (damag\$3)) and (substrate wafer semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/06 16:26
S48	42	((wall side side\$1wall) with (hole orifice cut\$1out opening) with (obstruct\$4 cover\$4 clos\$4 block\$4) with (prevent\$4 prohibit\$4) with (damag\$3)) and (substrate wafer semiconductor workpiece)	US-PGPUB; USPAT	OR	ON	2006/01/06 16:26

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S49	0	((wall side side\$1wall) with (hole orifice cut\$1out opening) with (obstruct\$4 cover\$4 clos\$4 block\$4) with (prevent\$4 prohibit\$4) with (damag\$3)) and ((substrate wafer semiconductor workpiece) same (cassette pod container "foup" "smif"))	US-PGPUB; USPAT	OR	ON	2006/01/06 16:27
S50	11	((wall side side\$1wall) with (hole orifice cut\$1out opening) with (prevent\$4 prohibit\$4) with (damag\$3)) and ((substrate wafer semiconductor workpiece) same (cassette pod container "foup" "smif"))	US-PGPUB; USPAT	OR	ON	2006/01/06 16:46
S51	17	((hole orifice cut\$1out opening) with (prevent\$4 prohibit\$4) with (damag\$3) with (substrate wafer semiconductor workpiece)) same (cassette pod container "foup" "smif")	US-PGPUB; USPAT	OR	ON	2006/01/06 16:52
S52	9	((hole orifice cut\$1out opening) with (prevent\$4 prohibit\$4) with (damag\$3) with (substrate wafer semiconductor workpiece)) same (cassette pod container "foup" "smif")	EPO; JPO; DERWENT	OR	ON	2006/01/06 16:48
S53	13	((hole orifice cut\$1out opening) with (prevent\$4 prohibit\$4) with (damag\$3) with (substrate wafer semiconductor workpiece)) and (cassette pod container "foup" "smif")	EPO; JPO; DERWENT	OR	ON	2006/01/06 16:48
S54	10	("3682083" "3877134" "4153164" "4176751" "4493418" "4600231" "4724963" "5308993" "5351836" "5364144").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 17:11
S55	9	("5638958").URPN.	USPAT	OR	ON	2006/01/06 17:25
S56	1	("5346518").PN.	US-PGPUB; USPAT	OR	OFF	2006/01/09 14:39
S57	326	156/345.31.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/09 14:53
S58	1820	((156/345.31) or (156/345.32) or (118/719)).CCLS.	US-PGPUB; USPAT	OR	OFF	2006/01/09 14:53
S59	618	S58 and (pod "foup" cassette pod "smif")	US-PGPUB; USPAT	OR	ON	2006/01/09 14:54
S60	77	S59 and ((hole orifice port) with (block\$3 obstruct\$3 cover\$3))	US-PGPUB; USPAT	OR	ON	2006/01/09 14:54
S61	21	S58 and ((pod "foup" cassette pod "smif") same ((hole orifice port) with (block\$3 obstruct\$3 cover\$3)))	US-PGPUB; USPAT	OR	ON	2006/01/09 14:55
S62	833	(electroless and plat\$3).ti.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/09 16:40
S63	1	("4532970").PN.	US-PGPUB; USPAT	OR	OFF	2006/06/13 18:31
S64	235	(118/715-733.ccls. 414/939-941.ccls.) and (cassette with seal\$3)	US-PGPUB; USPAT	OR	ON	2006/06/13 18:32